

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tatsumi TSUCHIYA</td> <td>02/21/2012</td> </tr> <tr> <td>Takashi SHIBANUMA</td> <td>02/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Tatsumi TSUCHIYA	02/21/2012	Takashi SHIBANUMA	02/21/2012						
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<table border="1"> <tr> <td>Name:</td> <td>DAIKIN INDUSTRIES, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>Umeda Center Building, 4-12, Nakazaki-Nishi,</td> </tr> <tr> <td>Internal Address:</td> <td>2-chome, Kita-ku, Osaka-shi,</td> </tr> <tr> <td>City:</td> <td>Osaka</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>530-8323</td> </tr> </table>		Name:	DAIKIN INDUSTRIES, LTD.	Street Address:	Umeda Center Building, 4-12, Nakazaki-Nishi,	Internal Address:	2-chome, Kita-ku, Osaka-shi,	City:	Osaka	State/Country:	JAPAN	Postal Code:	530-8323
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: 2027218250 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 2027218200 Email: wlp@wenderoth.com Correspondent Name: WENDEROTH, LIND & PONACK, LLP Address Line 1: 1030 15th Street, N.W. Address Line 2: Suite 400 East Address Line 4: Washington, DISTRICT OF COLUMBIA 20005</p>													
ATTORNEY DOCKET NUMBER:	2013_0544A												
NAME OF SUBMITTER:	Donna King												
Signature:	/Donna King/												

Date:

05/09/2013

Total Attachments: 2

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ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s) of Inventor(s) **1) Tatsumi TSUCHIYA, and 2) Takashi SHIBANUMA,** of
1)-2) c/o Yodogawa Seisakusho, DAIKIN INDUSTRIES, LTD., 1-1, Nishihitotsuya,
Settsu-shi, Osaka 5660044, Japan
the undersigned hereby sell(s) and assign(s) to
DAIKIN INDUSTRIES, LTD., of
Insert Name(s) of Assignee(s) Umeda Center Building, 4-12, Nakazaki-Nishi 2-Chome, Kita-ku, Osaka-shi, Osaka
Address 5308323, Japan
(hereinafter designated as the Assignee) the entire right, title and interest for the
United States as defined in 35 USC 100, in the invention known as

Title of Invention **HFO REFRIGERANT COMPOSITION HAVING IMPROVED SLIDABILITY**

for which an application for patent in the United States has been executed by the undersigned

Date of Signing of Application on February 21, 2012

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, D.C. 20006-1021, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date February 21, 2012, Name of the Inventor Tatsumi TSUCHIYA
Tatsumi TSUCHIYA

Date Feb. 21, 2012, Name of the Inventor Takashi Shibamura
Takashi SHIBANUMA

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness Seichiro Ochi

Witness Hajiro Ashiwara

ACKNOWLEDGMENT

_____ } ss

This _____ day of _____, 20____, before me personally came the above-named me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL

Official Signature

Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date _____

Applicant Reference Number _____ Atty Docket No. _____

Title of Invention _____